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Effect of a silicon dioxide diffusion barrier layer on the migration of strontium implanted into SiC

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Polycrystalline SiC wafers were implanted with 300 keV strontium ions at room temperature to a fluence of $2 \times 10^{16} \text{ cm}^{-2}$. Silicon dioxide (SiO₂) layers of about 100 nm thick were deposited onto the surface of implanted SiC via magnetron sputtering of a SiO₂ target in argon-oxygen atmosphere. The as-deposited (i.e., SiO₂/implanted SiC) samples were subjected to sequential isochronal annealing, under vacuum, at temperatures ranging from 1100 to 1400 °C in steps of 100 °C for 5 h. The effect of annealing on the surface topography and migration of strontium in SiC and SiO₂ layers were investigated by scanning electron microscopy (SEM), scanning transmission electron microscopy (STEM) and Rutherford backscattering spectrometry (RBS), respectively. RBS and STEM results showed that annealing at 1100 and 1200 °C, caused strong strontium segregation toward both SiO₂/SiC interface region and SiO₂ surface. The migration of strontium from SiC to the SiO₂ layer at 1100 and 1200 °C enhanced the sublimation of SiO₂ in an ultrahigh vacuum chamber, where the pure SiO₂ layer (i.e., without impurities) showed no sublimation after annealing under the same conditions. However, further annealing, at 1300 and 1400 °C, showed strong sublimation of the pure SiO₂ layer. This indicates that SiO₂ is not suitable for use as an additional diffusion barrier for SiC since temperatures in a nuclear reactor can reach 1600 °C during accident conditions.

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Footnotes

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